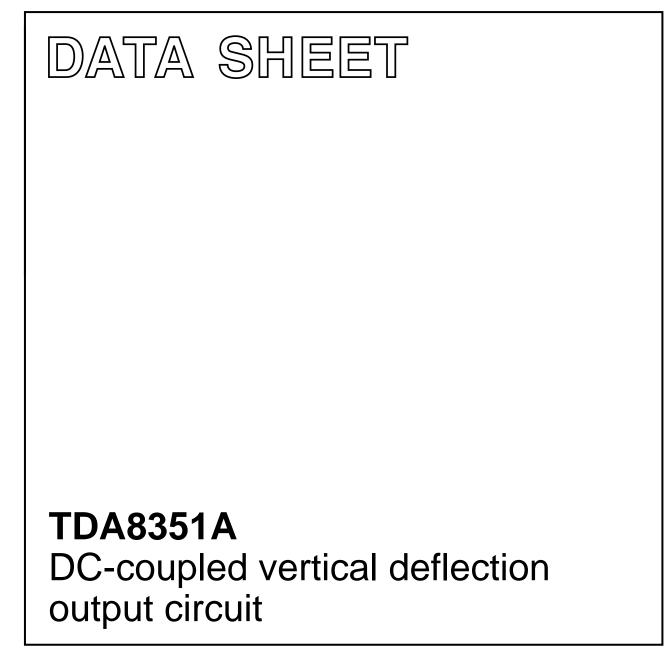
INTEGRATED CIRCUITS



Objective specification File under Integrated Circuits, IC02 January 1995

Philips Semiconductors





FEATURES

- Few external components
- Highly efficient fully DC-coupled vertical output bridge circuit
- Vertical flyback switch
- Guard circuit
- Protection against:
 - short-circuit of the output pins (9 and 5)
 - $-\,$ short-circuit of the output pins to V_P
- Temperature (thermal) protection
- High EMC immunity because of common mode inputs
- A guard signal in zoom mode.

QUICK REFERENCE DATA

GENERAL DESCRIPTION

The TDA8351A is a power circuit for use in 90° and 110° colour deflection systems for field frequencies of 50 to 120 Hz. The circuit provides a DC driven vertical deflection output circuit, operating as a highly efficient class G system.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
DC supply			-	-		-
V _P	supply voltage		9	16	25	V
lq	quiescent supply current		-	30	-	mA
Vertical circuit			·	•	·	·
I _{O(p-p)}	output current (peak-to-peak value)		_	-	3	A
I _{diff(p-p)}	differential input current (peak-to-peak value)		-	600	_	μΑ
V _{diff(p-p)}	differential input voltage (peak-to-peak value)		-	1.8	-	V
Flyback switch	•		•		·	ł
I _M	peak output current	t ≤ 1.5 ms	-	-	±1.5	A
V _{FB}	flyback supply voltage		-	-	50	V
		note 1	-	-	60	V
Thermal data (ii	n accordance with IEC 747-1)		•			
T _{stg}	storage temperature		-55	-	+150	°C
T _{amb}	operating ambient temperature		-25	-	+75	°C
T _{vi}	virtual junction		_	_	150	°C

Note

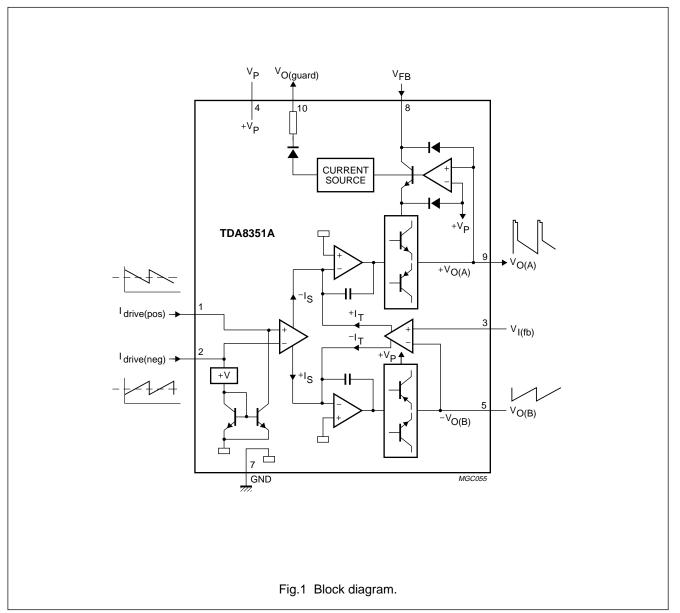
1. A flyback supply voltage of >50 V up to 60 V is allowed in application. A 220 nF capacitor in series with a 22 Ω resistor (dependent on I_O and the inductance of the coil) has to be connected between pin 7 and ground. The decoupling capacitor of V_{FB} has to be connected between pin 9 and pin 5. This supply voltage line must have a resistance of 33 Ω (see application circuit Fig.5).

TDA8351A

ORDERING INFORMATION

TYPE NUMBER		PACKAGE				
	NAME	NAME DESCRIPTION				
TDA8351A	DBS13P	plastic DIL-bent-SIL power package; 13 leads (lead length 12 mm)	SOT141-6			

BLOCK DIAGRAM

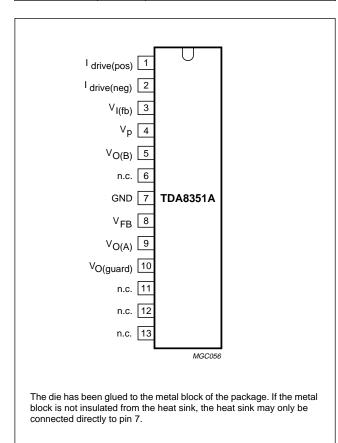


Objective specification

DC-coupled vertical deflection output circuit

PINNING

SYMBOL	PIN	DESCRIPTION
I _{drive(pos)}	1	input power-stage (positive); includes I _{I(sb)} signal bias
I _{drive(neg)}	2	input power-stage (negative); includes $I_{I(\text{sb})}$ signal bias
V _{I(fb)}	3	input feedback voltage
VP	4	supply voltage
V _{O(B)}	5	output voltage B
n.c.	6	not connected
GND	7	ground
V _{FB}	8	input flyback supply voltage
V _{O(A)}	9	output voltage A
V _{O(guard)}	10	guard output voltage
n.c.	11	not connected
n.c.	12	not connected
n.c.	13	not connected





TDA8351A

FUNCTIONAL DESCRIPTION

The vertical driver circuit is a bridge configuration. The deflection coil is connected between the output amplifiers, which are driven in phase opposition. An external resistor (R_M) connected in series with the deflection coil provides internal feedback information. The differential input circuit is voltage driven. The input circuit has been adapted to enable it to be used with the TDA9150, TDA9151B, TDA9160A, TDA9162, TDA8366 and TDA8367 which deliver symmetrical current signals. An external resistor (R_{CON}) connected between the differential input determines the output current through the deflection coil. The relationship between the differential input current and the output current is defined by: $I_{diff} \times R_{CON} = I_{coil} \times R_{M}$. The output current is adjustable from 0.5 A (p-p) to 3 A (p-p) by varying R_M. The maximum input differential voltage is 1.8 V. In the application it is recommended that $V_{diff} = 1.5 V$ (typ). This is recommended because of the spread of input current and the spread in the value of R_{CON}.

The flyback voltage is determined by an additional supply voltage V_{FB} . The principle of operating with two supply voltages (class G) makes it possible to fix the supply voltage V_P optimum for the scan voltage and the second supply voltage V_{FB} optimum for the flyback voltage. Using this method, very high efficiency is achieved.

The supply voltage V_{FB} is almost totally available as flyback voltage across the coil, this being possible due to the absence of a decoupling capacitor (not necessary, due to the bridge configuration). The output circuit is fully protected against the following:

- thermal protection
- short-circuit protection of the output pins (pins 5 and 9)
- short-circuit of the output pins to V_P.

A guard circuit $V_{O(guard)}$ is provided. The guard circuit is activated at the following conditions:

- during flyback
- during short-circuit of the coil and during short-circuit of the output pins (pins 5 and 9) to V_P or ground
- during open loop
- when the thermal protection is activated.

This signal can be used for blanking the picture tube screen.

TDA8351A

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
DC supply					1
V _P	supply voltage	non-operating	-	40	V
			_	25	V
V _{FB}	flyback supply voltage		_	50	V
		note 1	_	60	V
Vertical circuit			L.	ł	
I _{O(p-p)}	output current (peak-to-peak value)	note 2	-	3	А
V _{O(A)}	output voltage (pin 7)		_	52	V
		note 1	_	62	V
Flyback switch					•
I _M	peak output current		-	±1.5	А
Thermal data (ii	n accordance with IEC 747-1)			ł	
T _{stg}	storage temperature		-55	+150	°C
T _{amb}	operating ambient temperature		-25	+75	°C
T _{vj}	virtual junction temperature		_	150	°C
R _{th vj-c}	resistance v _j -case		_	4	K/W
R _{th vj-a}	resistance vj-ambient in free air		_	40	K/W
t _{sc}	short-circuiting time	note 3	_	1	hr

Notes

- 1. A flyback supply voltage of >50 V up to 60 V is allowed in application. A 220 nF capacitor in series with a 22 Ω resistor (dependent on I_O and the inductance of the coil) has to be connected between pin 7 and ground. The decoupling capacitor of V_{FB} has to be connected between pin 6 and pin 3. This supply voltage line must have a resistance of 33 Ω (see application circuit Fig.5).
- 2. I_O maximum determined by current protection.
- 3. Up to $V_P = 18 V$.

TDA8351A

CHARACTERISTICS

 V_P = 17.5 V; V_{FB} = 45 V; f_i = 50 Hz; $I_{I(sb)}$ = 400 μ A; T_{amb} = 25 °C; measured in test circuit of Fig.3; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	
DC supply						•
V _P	operating supply voltage		9.0	_	25	V
V _{FB}	flyback supply voltage		VP	_	50	V
		note 1	V _P	_	60	V
I _P	supply current	no signal; no load	_	30	55	mA
Vertical cir	cuit			1		•
Vo	output voltage swing (scan)	$\begin{split} I_{diff} &= 0.6 \text{ mA (p-p);} \\ V_{diff} &= 1.8 \text{ V (p-p);} \\ I_{O} &= 3 \text{ A (p-p)} \end{split}$	19.8	-	-	V
LE	linearity error	I _O = 3 A (p-p); note 2	-	1	2	%
		I _O = 50 mA (p-p); note 2	-	1	2	%
Vo	output voltage swing (flyback) V _{O(A)} - V _{O(B)}	$I_{diff} = 0.3 \text{ mA};$ $I_O = 1.5 \text{ A (M)}$	-	39	-	V
V _{DF}	forward voltage of the internal efficiency diode (V _{O(A)} - V _{FB})	$I_O = -1.5 \text{ A (M)};$ $I_{diff} = 0.3 \text{ mA}$	-	-	1.5	V
I _{os}	output offset current	I _{diff} = 0; I _{l(sb)} = 50 to 500 μA	-	-	30	mA
V _{os}	offset voltage at the input of the feedback amplifier ($V_{I(fb)}$ - $V_{O(B)}$)	$I_{diff} = 0;$ $I_{1(sb)} = 50 \text{ to } 500 \mu\text{A}$	-	-	18	mV
$\Delta V_{os} T$	output offset voltage as a function of temperature	I _{diff} = 0	-	-	72	μV/K
V _{O(A)}	DC output voltage	I _{diff} = 0; note 3	_	8.0	-	V
G _{vo}	open-loop voltage gain (V ₇₋₄ /V ₁₋₂)	notes 4 and 5	_	80	_	dB
	open loop voltage gain $(V_{7-4}/V_{9-4}; V_{1-2} = 0)$	note 4	-	80	-	dB
V _R	voltage ratio V ₁₋₂ /V ₉₋₄		-	0	_	dB
f _{res}	frequency response (-3 dB)	open loop; note 6	-	40	-	Hz
GI	current gain (I _O /I _{diff})		_	5000	_	
∆G _c T	current gain drift as a function of temperature		-	-	10 ⁻⁴	К
I _{I(sb)}	signal bias current		50	400	500	μA
I _{FB}	flyback supply current	during scan	-	_	100	μA
PSRR	power supply ripple rejection	note 7	-	80	-	dB
V _{I(DC)}	DC input voltage		-	2.7	-	V
V _{I(CM)}	common mode input voltage	$I_{I(sb)} = 0$	0	_	1.6	V
I _{bias}	input bias current	$I_{I(sb)} = 0$	_	0.1	0.5	μA
I _{O(CM)}	common mode output current	$\Delta I_{I(sb)} = 300 \ \mu A \ (p-p);$ $f_i = 50 \ Hz; \ I_{diff} = 0$	-	0.2	-	mA

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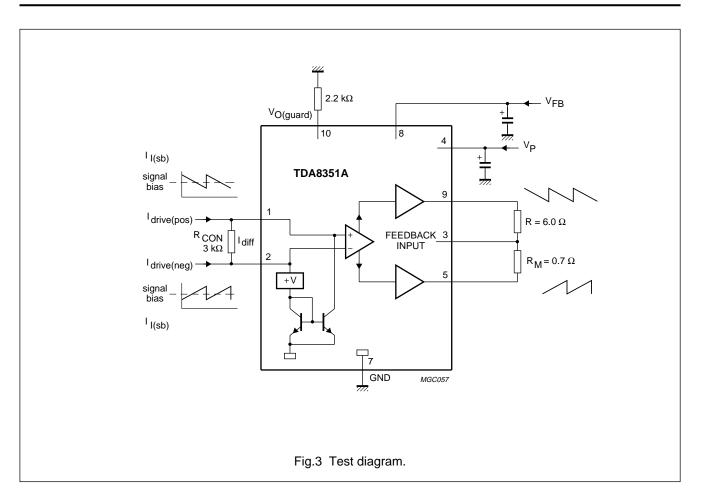
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Guard circu	uit			·		-
IO	output current	not active; V _{O(guard)} = 0 V	-	-	50	μA
		active; V _{O(guard)} = 4.5 V	1	-	2.5	mA
V _{O(guard)}	output voltage on pin 8	I _O = 100 μA	-	-	5.5	V
	allowable voltage on pin 8	maximum leakage current = 10 μA;	-	_	40	V

Notes

- 1. A flyback supply voltage of >50 V up to 60 V is allowed in application. A 220 nF capacitor in series with a 22 Ω resistor (dependent on I_O and the inductance of the coil) has to be connected between pin 7 and ground. The decoupling capacitor of V_{FB} has to be connected between pin 9 and pin 5. This supply voltage line must have a resistance of 33 Ω (see application circuit Fig.5).
- The linearity error is measured without S-correction and based on the same measurement principle as performed on the screen. The measuring method is as follows: Divide the output signal I₅ - I₉ (V_{RM}) into 22 equal parts ranging from 1 to 22 inclusive. Measure the value of two succeeding parts called one block starting with part 2 and 3 (block 1) and ending with part 20 and 21 (block 10). Thus part 1 and 22 are unused. The equations for linearity error for adjacent blocks (LEAB) and not adjacent blocks (NAB) are given below

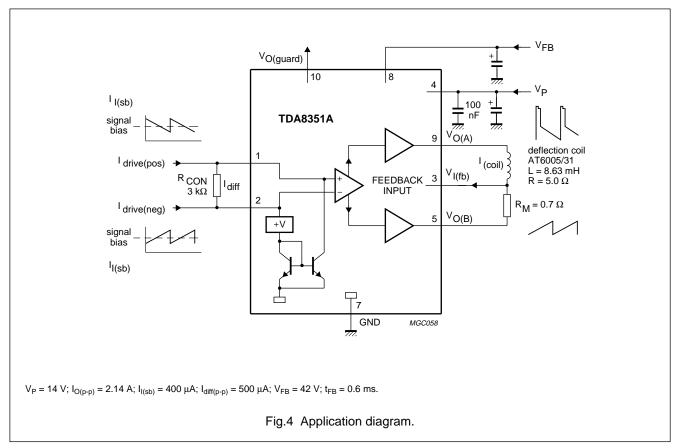
$$\mathsf{LEAB} = \frac{\mathsf{a}_{k} - \mathsf{a}_{(k+1)}}{\mathsf{a}_{avq}}; \mathsf{NAB} = \frac{\mathsf{a}_{max} - \mathsf{a}_{min}}{\mathsf{a}_{avq}}$$

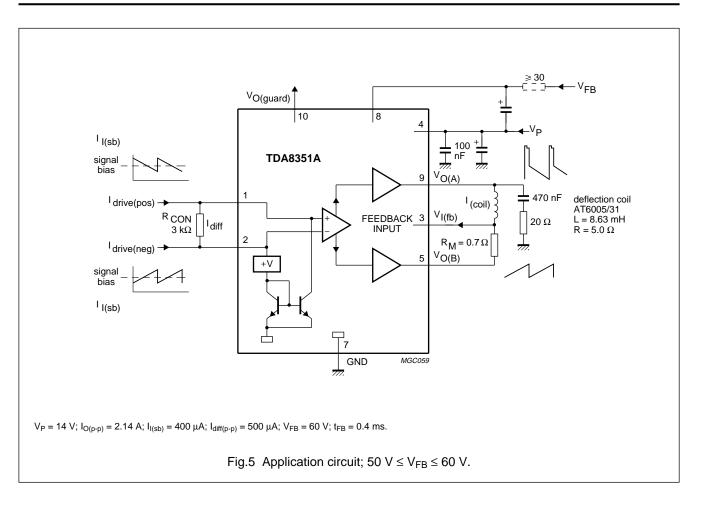
- 3. Referenced to V_P.
- 4. V values within formulae, relate to voltages at or between relative pin numbers, i.e. V₉₋₅/V₁₋₂ = voltage value across pins 7 and 4 divided by voltage value across pins 1 and 2.
- 5. V_{9-4} AC short-circuited.
- 6. Frequency response V_{9-5}/V_{3-5} is equal to frequency response V_{9-5}/V_{1-2} .
- 7. At $V_{(ripple)}$ = 500 mV eff; measured across R_M ; f_i = 50 Hz.



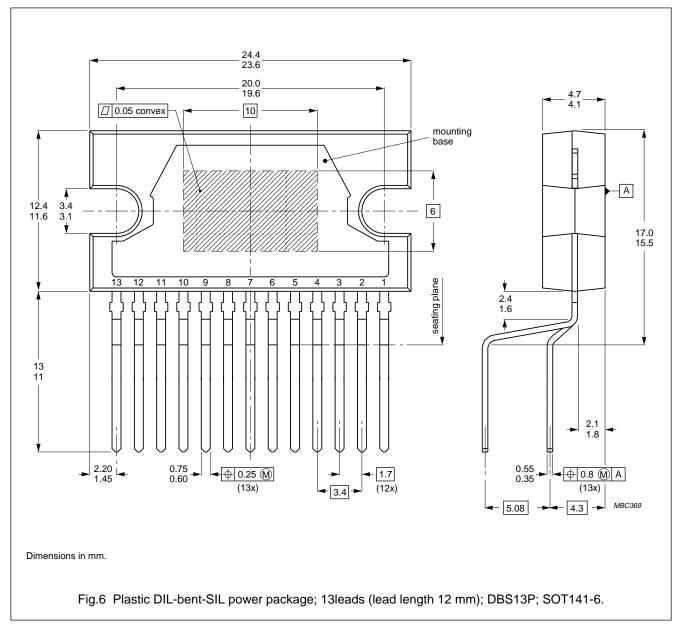
TDA8351A

APPLICATION INFORMATION





PACKAGE OUTLINE



TDA8351A

SOLDERING

Plastic DIL-bent-SIL packages

BY DIP OR WAVE

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 s. The total contact time of successive solder waves must not exceed 5 s.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below $300 \,^{\circ}$ C, it must not be in contact for more than 10 s; if between 300 and 400 $^{\circ}$ C, for not more than 5 s.

DEFINITIONS

Data sheet status				
Objective specification	Objective specification This data sheet contains target or goal specifications for product development.			
Preliminary specification	Preliminary specification This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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Argentina: IEROD, Av. Juramento 1992 - 14.b, (1428) BUENOS AIRES, Tel. (541)786 7633, Fax. (541)786 9367 Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113, Tel. (02)805 4455, Fax. (02)805 4466 Austria: Triester Str. 64, A-1101 WIEN, P.O. Box 213, Tel. (01)60 101-1236, Fax. (01)60 101-1211 Belgium: Postbus 90050, 5600 PB EINDHOVEN, The Netherlands, Tel. (31)40 783 749, Fax. (31)40 788 399 Brazil: Rua do Rocio 220 - 5th floor, Suite 51, CEP: 04552-903-SÃO PAULO-SP, Brazil. P.O. Box 7383 (01064-970). Tel. (011)821-2333, Fax. (011)829-1849 Canada: PHILIPS SEMICONDUCTORS/COMPONENTS: Tel. (800) 234-7381, Fax. (708) 296-8556 Chile: Av. Santa Maria 0760, SANTIAGO, Tel. (02)773 816, Fax. (02)777 6730 Colombia: IPRELENSO LTDA, Carrera 21 No. 56-17, 77621 BOGOTA, Tel. (571)249 7624/(571)217 4609, Fax. (571)217 4549 Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S, Tel. (032)88 2636, Fax. (031)57 1949 Finland: Sinikalliontie 3, FIN-02630 ESPOO, Tel. (9)0-50261, Fax. (9)0-520971 France: 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex, Tel. (01)4099 6161, Fax. (01)4099 6427 Germany: P.O. Box 10 63 23, 20043 HAMBURG, Tel. (040)3296-0, Fax. (040)3296 213. Greece: No. 15, 25th March Street, GR 17778 TAVROS, Tel. (01)4894 339/4894 911, Fax. (01)4814 240 Hong Kong: PHILIPS HONG KONG Ltd., 6/F Philips Ind. Bldg., 24-28 Kung Yip St., KWAI CHUNG, N.T., Tel. (852)424 5121, Fax. (852)428 6729 India: Philips INDIA Ltd, Shivsagar Estate, A Block , Dr. Annie Besant Rd. Worli, Bombay 400 018 Tel. (022)4938 541, Fax. (022)4938 722 Indonesia: Philips House, Jalan H.R. Rasuna Said Kav. 3-4, P.O. Box 4252, JAKARTA 12950, Tel. (021)5201 122, Fax. (021)5205 189 Ireland: Newstead, Clonskeagh, DUBLIN 14, Tel. (01)640 000, Fax. (01)640 200 Italy: PHILIPS SEMICONDUCTORS S.r.I. Piazza IV Novembre 3, 20124 MILANO Tel. (0039)2 6752 2531, Fax. (0039)2 6752 2557 Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108, Tel. (03)3740 5028, Fax. (03)3740 0580 Korea: (Republic of) Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL, Tel. (02)794-5011, Fax. (02)798-8022 Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR, Tel. (03)750 5214, Fax. (03)757 4880 Mexico: 5900 Gateway East, Suite 200, EL PASO, TX 79905, Tel. 9-5(800)234-7381, Fax. (708)296-8556 Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB Tel. (040)783749, Fax. (040)788399 New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND, Tel. (09)849-4160, Fax. (09)849-7811 Norway: Box 1, Manglerud 0612, OSLO, Tel. (022)74 8000, Fax. (022)74 8341

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For all other countries apply to: Philips Semiconductors, International Marketing and Sales, Building BE-p, P.O. Box 218, 5600 MD, EINDHOVEN, The Netherlands, Telex 35000 phtcnl, Fax. +31-40-724825

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Printed in The Netherlands

533061/1500/01/pp16 Document order number: Date of release: January 1995 9397 744 90011

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